SPECIFICATIONS FOR NICHIA WHITE LED

 $\mathsf{MODEL}:\ NSPW500BS$

NICHIA CORPORATION

1.SPECIFICATIONS

(1) Absolute Maximum Rating

(Ta=25)

1) 110001410 1114/111141111 11411115			(14 25)
Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	IF	30	mA
Pulse Forward Current	IFP	100	mA
Reverse Voltage	VR	5	V
Power Dissipation	PD	120	mW
Operating Temperature	Topr	- 30 ~ + 85	
Storage Temperature	Tstg	- 40 ~ + 100	
Lead Soldering Temperature	Tsol	260 ± 5 for 5sec.	

IFP Conditions: Pulse Width 10msec. and Duty 1/10

(2) Initial Electrical/Optical Characteristics

(Ta=25)

Item		Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage		VF	I _F =20[mA]	-	3.6	4.0	V
Reverse Current		Ir	V _R = 5[V]	-	-	50	μA
Luminous Intensity	Rank S	Iv	I _F =20[mA]	6800	8000	9500	mcd
	Rank R	Iv	IF=20[mA]	4800	5600	6800	mcd
	Rank Q	Iv	I _F =20[mA]	3400	4000	4800	mcd

Measurement Uncertainty of the Luminous Intensity: ± 10%

One delivery will include three different ranks of products. The quantity-ratio of the three ranks is decided by Nichia.

Color Ranks

(IF=20mA,Ta=25

0.385

0.351

	Rank a0					
X	0.280	0.264	0.283	0.296		
У	0.248	0.267	0.305	0.276		

у	0.295	0.305	0.360	0.339			
Rank c0							
X	0.330	0.330	0.361	0.356			

0.360

Rank b1 0.287 | 0.283 | 0.330 | 0.330

	Rank b2					
X	0.296	0.287	0.330	0.330		
y	0.276	0.295	0.339	0.318		

Measurement Uncertainty of the Color Coordinates : ± 0.02

One delivery will include the consecutive two ranks of products. The quantity-ratio of the two ranks is decided by Nichia.

0.318

Luminous Intensity

2dillilous intensity			
Ranking by Luminous Intensity Ranking by Color Coordinates	Q	R	S
a0			
b1			
b2			
c0			

Shaded ranks are available.

2.TYPICAL INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS

Please refer to figure's page.

3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to f figure's page.

Material as follows; Resin : Epoxy

Leadframe : Ag plating Copper alloy

4.PACKAGING

Please refer to figure's page.

The label on the minimum packing unit bag shows;

Part Number, Lot Number, Quantity, Ranking

5.LOT NUMBER

The first six digits number shows **lot number**.

The lot number is composed of the following characters;

$\times \times \times \times$ -

- Year (9 for 1999, 0 for 2000)
- Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)

 $\times \times \times \times$ - Nichia's Product Number

- Ranking by Color Coordinates
- Ranking by Luminous Intensity

6.RELIABILITY

(1) TEST ITEMS AND RESULTS

(1) TEST TIEMS AND RI	Standard			Number of
Test Item	Test Method	Test Conditions	Note	Damaged
Resistance	JIS C 7021	$Tsol=260 \pm 5 , 10sec.$	1 time	0/100
to Soldering Heat	(1977)A-1	3mm from the base of the epoxy bulb		
Solderability	JIS C 7021	$Tsol=235 \pm 5$, $5sec.$	1 time	0/100
	(1977)A-2	(using flux)	over 95%	
Heat Shock	JIS C 7021	0 ~ 100	100 cycles	0/100
	(1977)A-3	5sec. 15sec.		
Temperature Cycle	JIS C 7021	-40 ~ 25 ~ 100 ~ 25	100 cycles	0/100
	(1977)A-4	30min. 5min. 30min. 5min.		
High Humidity	JIS C 7021	30 ~65 ~-10	10 cycles	0/100
Heat Cycle	(1977)A-5	90%RH 24hrs./1cycle		
Mechanical Strength	JIS C 7021	Load 2.5N (0.25kgf)	No noticeable	0/100
of Terminal (bend test)	(1977)A-11	$0\degree \sim 90\degree \sim 0\degree$ bend 3 times	damage	
Mechanical Strength	JIS C 7021	Load 10N (1kgf)	No noticeable	0/100
of Terminal (pull test)	(1977)A-11	30 ± 1 sec.	damage	
High Temperature	JIS C 7021	Ta=100	1000hrs.	0/100
Storage	(1977)B-10			
Humidity Heat	JIS C 7021	Ta=60 , RH=90%	1000hrs.	0/100
Load	(1977)B-11			
Low Temperature	JIS C 7021	Ta=-40	1000hrs.	0/100
Storage	(1977)B-12			
Life Test	JIS C 7035	Ta=25 , IF=30mA	1000hrs.	0/100
	(1985)			
High Humidity		60 , RH=90%, I _F =20mA	500hrs.	0/100
Heat Life Test			10001	
Low Temperature		Ta=-30 , IF=20mA	1000hrs.	0/100
Life Test				

(2) CRITERIA FOR JUDGING THE DAMAGE

			Criteria for Judgement		
Item	Symbol	Test Conditions	Min.	Max.	
Forward Voltage	VF	IF=20mA	-	U.S.L.*) × 1.1	
Reverse Current	Ir	$V_R=5V$	-	$U.S.L.*) \times 2.0$	
Luminous Intensity	Iv	I _F =20mA	L.S.L.**) \times 0.7	-	

*) U.S.L.: Upper Standard Level

**) L.S.L.: Lower Standard Level

7.CAUTIONS

White LEDs are devices which are materialized by combining Blue LEDs and special phosphors. Consequently, the color of White LEDs is changed a little by an operating current. Care should be taken after due consideration when using LEDs.

(1) Lead Forming

- When forming leads, the leads should be bent at a point at least 3mm from the base of the epoxy bulb. Do not use the base of the leadframe as a fulcrum during lead forming.
- Lead forming should be done before soldering.
- Do not apply any bending stress to the base of the lead. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- When mounting the LEDs onto a printed circuit board, the holes on the circuit board should be exactly aligned with the leads of the LEDs. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

(2) Soldering Conditions

- The leadframes of Nichia LEDs are made of copper-allay by special considering of heat conductance, so that very careful attention must be paid for the handling when soldering the LEDs.
- Solder the LEDs no closer than 3mm from the base of the epoxy bulb. Soldering the LEDs beyond the tie-bar is recommended.

· Maximum Allowable Soldering Conditions

	Soldering	Solder Dipping		
Soldering Iron	: 30W Max.	Pre-Heat : 100 Max.		
		Pre-Heat Time : 60 seconds Max.		
Temperature	: 300 Max.	Solder Bath Temperature : 260 Max.		
Soldering Time	: 3 seconds Max.	Dipping Time : 5 seconds Max.		
Position	: No closer than 3 mm from the base	Dipping Position : No lower than 3 mm from the		
	of the epoxy bulb.	base of the epoxy bulb.		

- Do not apply any stress to the lead particularly when heated.
- The LEDs must not be repositioned after soldering.
- After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused from warping of the PC board or from the clinching and cutting of the lead frames. When it is absolutely necessary, the LEDs may be mounted in this fashion but the User will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage such as wire bond failure or resin deterioration will occur. Nichia's LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause failure of the LEDs.

(3) Heat Generation

- Heat generation must be taken into design consideration when using the LEDs. The coefficient
 of temperature increase per input electric power at room temperature is about 0.5 degrees C/mW at the
 LED's active layer. This temperature gets higher when the LEDs are densely mounted.
 It is necessary to design the circuit so that the operating conditions are within the absolute maximum ratings.
- The operating current should be decided after considering the ambient maximum temperature when the LEDs are illuminating.

(4) Static Electricity

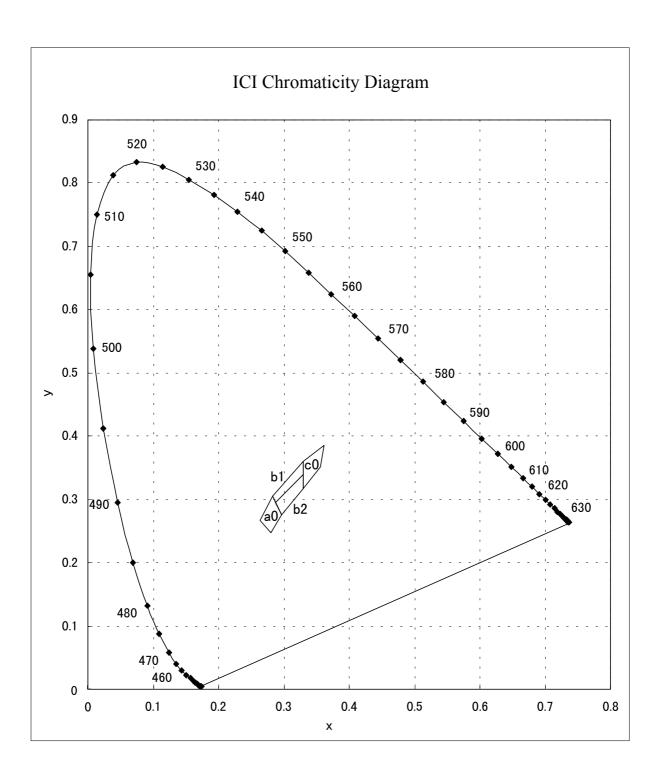
- Static electricity and surge will damage the LEDs. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipment and machinery must be properly grounded .
- When inspecting own final products on which LEDs were mounted, it is recommended to check also whether the mounted LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by light emission test at lower current (below 1mA is recommended).
- Damaged LEDs will show some unusual characteristics such as leak current remarkably increases, starting forward voltage becomes lower, or the LEDs get unlighted at the low current.

(5) Cleaning

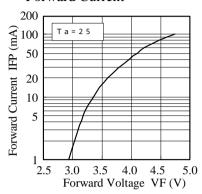
- Avoid exposure to chemicals as they may attack the LED epoxy and cause discoloration. When washing is required, isopropyl alcohol should be used.
- The influence of ultrasonic cleaning on the LEDs differs depending on factors such as oscillator output and how the LEDs are mounted. Before cleaning by ultrasonic wave, testing should be performed to ensure this will not cause damage to the LEDs.

(6) Others

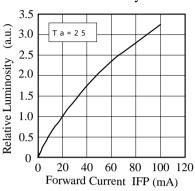
- Care must be taken so that reverse voltage will not exceed the absolute maximum rating when using LEDs with matrix drive.
- The leads are plated with silver. They will become discolored by contact with hydrogen sulfide
 and other gaseous chemicals. Precautions must be taken to maintain a clean storing atmosphere.
 Also, if the LEDs are stored for 3 months or more after being shipped from Nichia, a sealed container
 with a nitrogen atmosphere should be used for storage.
- The LED light output is strong enough to injure human eyes. Precautions must be taken to prevent looking directly at the LEDs with unaided eyes for more than a few seconds.
- These LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances). Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability—are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, automobiles, traffic control equipment, life support systems and safety devices.)
- User shall not reverse engineer by disassembling or analysis of the LEDs without having the prior written consent of Nichia. When defective LEDs are found, User shall inform to Nichia directly before disassembling or analysis.
- The formal specifications must be exchanged and signed by both parties before large volume purchase begins.
- The appearance and specifications of the product may be modified for improvement without notice.



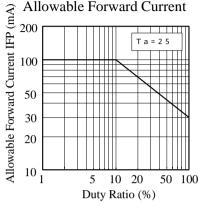
Forward Voltage vs. Forward Current



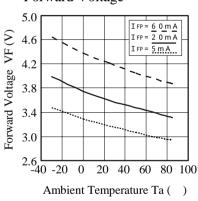
Forward Current vs. Relative Luminosity



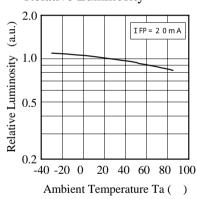
Duty Ratio vs.
Allowable Forward Current



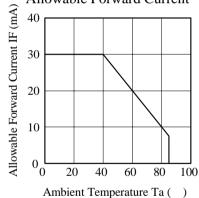
Ambient Temperature vs. Forward Voltage



Ambient Temperature vs. Relative Luminosity



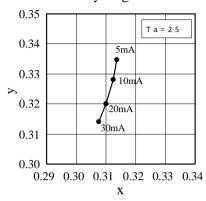
Ambient Temperature vs.
Allowable Forward Current



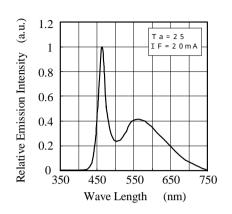


	Model	NSPWxxxx
Ţ	Title TY	P.CHARACTERISTICS
	No.	000728906042

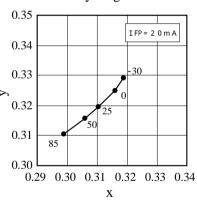
Forward Current vs. Chromaticity diagram



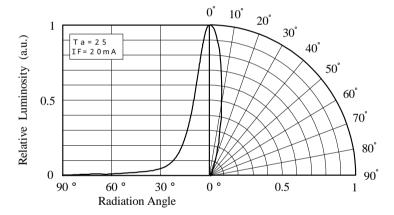
Spectrum



Ambient Temperature vs. Chromaticity diagram



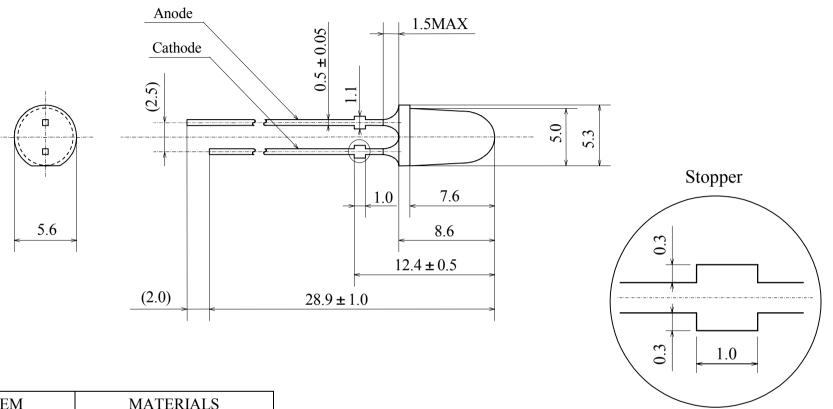
Directivity (NSPW500BS)



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		т .

	Model	NSPW500BS	/
1	Title T	YP.CHARACTERISTICS	
	No.	000728906082	

Nichia STLD-CW0164B <Cat.No.000728>



ITEM	MATERIALS		
RESIN(MOLD)	Ероху		
LEAD FRAME	Ag Plating Copper alloy		

Remark:

Bare copper alloy is exposed at tie-bar portion after cutting.

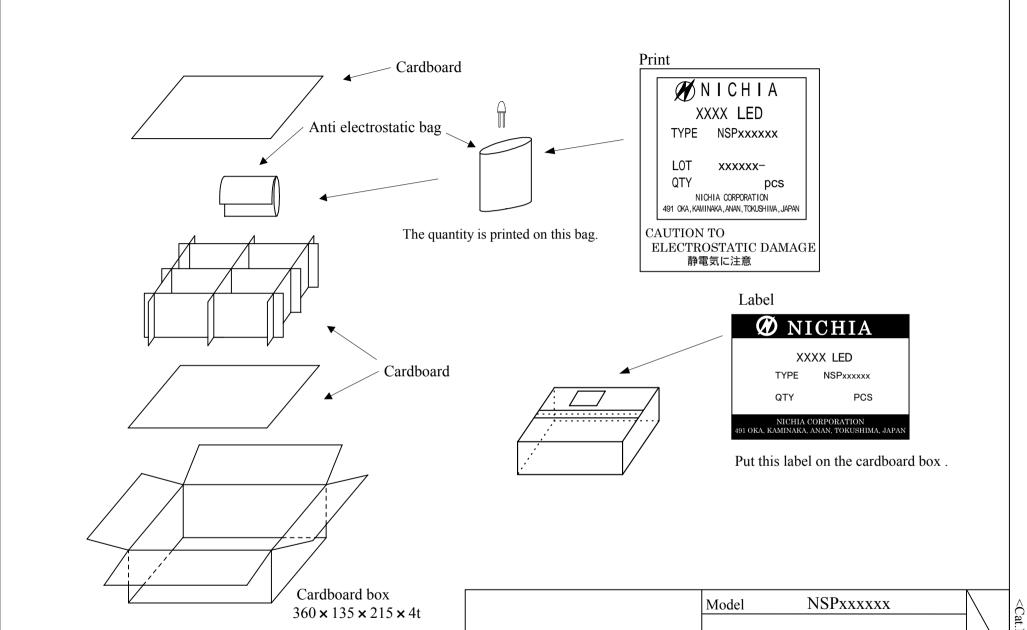
The lamps have sharp and hard points that may injure human eyes or fingers etc. ,so please pay enough care in the handling.

NICHIA CORPORATION	Model	NSPW500BS	Unit
	Title	OUTLINE DIMENSIONS	3/1 Scale
	No.	000728908091	Allow ± 0.2

Nichia STLD-CW0164 <Cat.No.000728



One box contains 8 bags at maximum.



NICHIA CORPORATION

Title

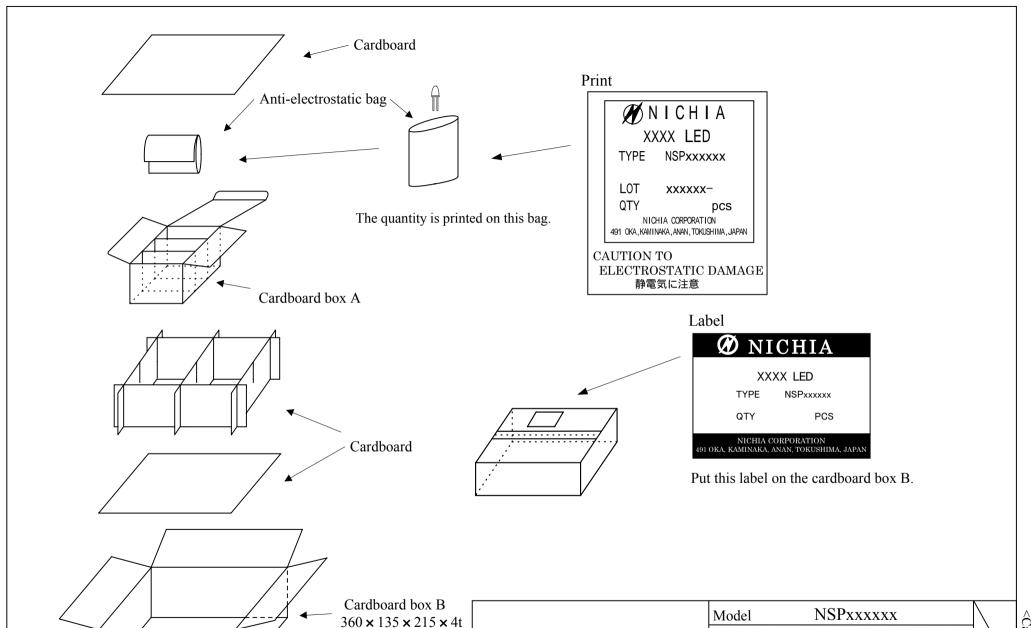
No.

PACKING

000728801062

Nichia STLD-CW0164B <Cat.No.000728>





The cardboard box B contains 2 cardboard box A at maximum.

NICHIA CORPORATION

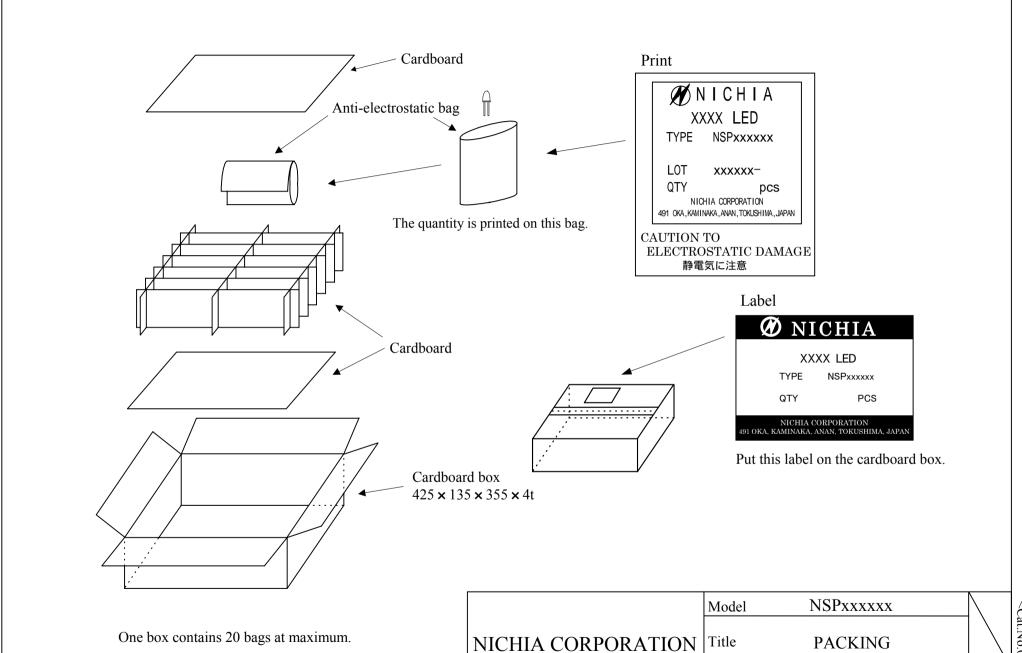
Title

No.

PACKING

000728801052

	Nichia
<cat.no.000728></cat.no.000728>	STLD-CW0164B

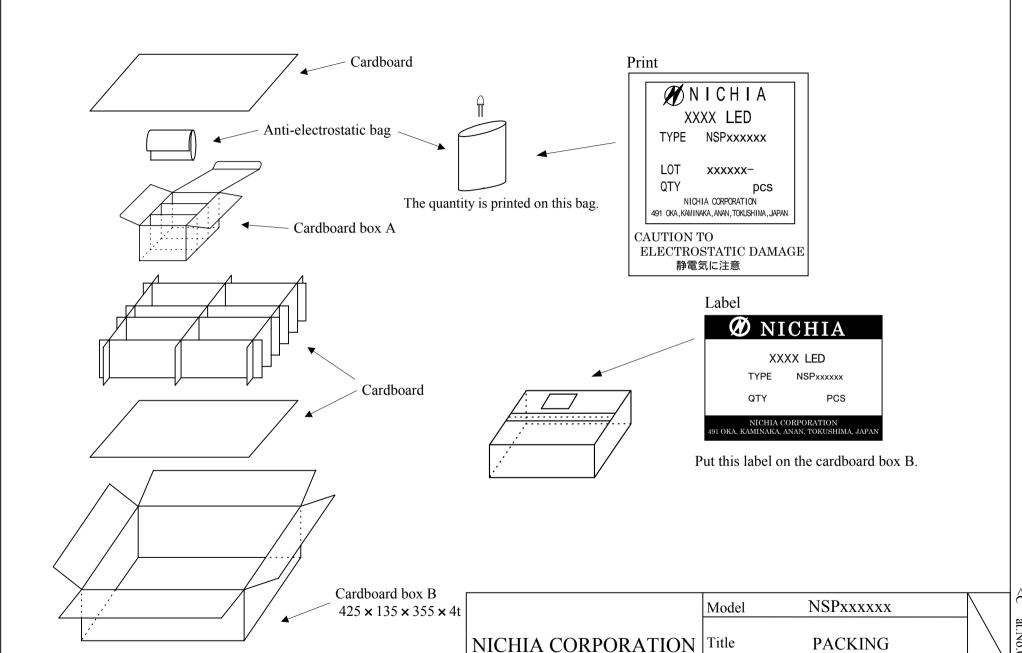


Nichia STLD-CW0164B <Cat.No.000728>

000728800982

No.

The cardboard box B contains 4 cardboard box A at maximum.



Nichia STLD-CW0164B <C at.No.000728>

000728801132

No.